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Scanning Electron Microscopy and X-Ray Microanalysis

Fourth Edition

Contents

1	Electron Beam—Specimen Interactions: Interaction Volume	1
1.1	What Happens When the Beam Electrons Encounter Specimen Atoms?.....	2
1.2	Inelastic Scattering (Energy Loss) Limits Beam Electron Travel in the Specimen	2
1.3	Elastic Scattering: Beam Electrons Change Direction of Flight	4
1.3.1	How Frequently Does Elastic Scattering Occur?.....	4
1.4	Simulating the Effects of Elastic Scattering: Monte Carlo Calculations	5
1.4.1	What Do Individual Monte Carlo Trajectories Look Like?.....	6
1.4.2	Monte Carlo Simulation To Visualize the Electron Interaction Volume.....	6
1.4.3	Using the Monte Carlo Electron Trajectory Simulation to Study the Interaction Volume.....	8
1.5	A Range Equation To Estimate the Size of the Interaction Volume	12
	References.....	14
2	Backscattered Electrons	15
2.1	Origin	16
2.1.1	The Numerical Measure of Backscattered Electrons.....	16
2.2	Critical Properties of Backscattered Electrons	16
2.2.1	BSE Response to Specimen Composition (η vs. Atomic Number, Z).....	16
2.2.2	BSE Response to Specimen Inclination (η vs. Surface Tilt, θ).....	20
2.2.3	Angular Distribution of Backscattering.....	22
2.2.4	Spatial Distribution of Backscattering.....	23
2.2.5	Energy Distribution of Backscattered Electrons.....	27
2.3	Summary	27
	References.....	28
3	Secondary Electrons	29
3.1	Origin	30
3.2	Energy Distribution	30
3.3	Escape Depth of Secondary Electrons	30
3.4	Secondary Electron Yield Versus Atomic Number	30
3.5	Secondary Electron Yield Versus Specimen Tilt	34
3.6	Angular Distribution of Secondary Electrons	34
3.7	Secondary Electron Yield Versus Beam Energy	35
3.8	Spatial Characteristics of Secondary Electrons	35
	References.....	37
4	X-Rays	39
4.1	Overview	40
4.2	Characteristic X-Rays	40
4.2.1	Origin.....	40
4.2.2	Fluorescence Yield.....	41
4.2.3	X-Ray Families.....	42
4.2.4	X-Ray Nomenclature.....	43
4.2.5	X-Ray Weights of Lines.....	44
4.2.6	Characteristic X-Ray Intensity.....	44
4.3	X-Ray Continuum (<i>bremstrahlung</i>)	47
4.3.1	X-Ray Continuum Intensity.....	49
4.3.2	The Electron-Excited X-Ray Spectrum, As-Generated.....	49
4.3.3	Range of X-ray Production.....	50
4.3.4	Monte Carlo Simulation of X-Ray Generation.....	51
4.3.5	X-ray Depth Distribution Function, $\phi(\rho z)$	53

4.4	X-Ray Absorption	54
4.5	X-Ray Fluorescence	59
	References.....	63
5	Scanning Electron Microscope (SEM) Instrumentation	65
5.1	Electron Beam Parameters	66
5.2	Electron Optical Parameters	66
5.2.1	Beam Energy	66
5.2.2	Beam Diameter.....	67
5.2.3	Beam Current	67
5.2.4	Beam Current Density	68
5.2.5	Beam Convergence Angle, α	68
5.2.6	Beam Solid Angle.....	69
5.2.7	Electron Optical Brightness, β	70
5.2.8	Focus.....	71
5.3	SEM Imaging Modes	75
5.3.1	High Depth-of-Field Mode.....	75
5.3.2	High-Current Mode.....	78
5.3.3	Resolution Mode.....	80
5.3.4	Low-Voltage Mode	81
5.4	Electron Detectors	83
5.4.1	Important Properties of BSE and SE for Detector Design and Operation.....	83
5.4.2	Detector Characteristics	83
5.4.3	Common Types of Electron Detectors.....	85
5.4.4	Secondary Electron Detectors.....	86
5.4.5	Specimen Current: The Specimen as Its Own Detector.....	88
5.4.6	A Useful, Practical Measure of a Detector: Detective Quantum Efficiency.....	89
	References.....	91
6	Image Formation	93
6.1	Image Construction by Scanning Action	94
6.2	Magnification	95
6.2.1	Magnification, Image Dimensions, and Scale Bars.....	95
6.3	Making Dimensional Measurements With the SEM: How Big Is That Feature?	95
6.3.1	Calibrating the Image.....	95
6.4	Image Defects	98
6.4.1	Projection Distortion (Foreshortening)	98
6.4.2	Image Defocusing (Blurring).....	100
6.5	Making Measurements on Surfaces With Arbitrary Topography: Stereomicroscopy	102
6.5.1	Qualitative Stereomicroscopy	103
6.5.2	Quantitative Stereomicroscopy	107
	References.....	110
7	SEM Image Interpretation	111
7.1	Information in SEM Images	112
7.2	Interpretation of SEM Images of Compositional Microstructure	112
7.2.1	Atomic Number Contrast With Backscattered Electrons.....	112
7.2.2	Calculating Atomic Number Contrast	113
7.2.3	BSE Atomic Number Contrast With the Everhart–Thornley Detector	113
7.3	Interpretation of SEM Images of Specimen Topography	114
7.3.1	Imaging Specimen Topography With the Everhart–Thornley Detector	115
7.3.2	The Light-Optical Analogy to the SEM/E–T (Positive Bias) Image	116
7.3.3	Imaging Specimen Topography With a Semiconductor BSE Detector	119
	References.....	121

8	The Visibility of Features in SEM Images	123
8.1	Signal Quality: Threshold Contrast and Threshold Current	124
	References	131
9	Image Defects	133
9.1	Charging	134
9.1.1	What Is Specimen Charging?	134
9.1.2	Recognizing Charging Phenomena in SEM Images	135
9.1.3	Techniques to Control Charging Artifacts (High Vacuum Instruments)	139
9.2	Radiation Damage	142
9.3	Contamination	143
9.4	Moiré Effects: Imaging What Isn't Actually There	144
	References	146
10	High Resolution Imaging	147
10.1	What Is "High Resolution SEM Imaging"?	148
10.2	Instrumentation Considerations	148
10.3	Pixel Size, Beam Footprint, and Delocalized Signals	148
10.4	Secondary Electron Contrast at High Spatial Resolution	150
10.4.1	SE range Effects Produce Bright Edges (Isolated Edges)	151
10.4.2	Even More Localized Signal: Edges Which Are Thin Relative to the Beam Range	152
10.4.3	Too Much of a Good Thing: The Bright Edge Effect Can Hinder Distinguishing Shape	153
10.4.4	Too Much of a Good Thing: The Bright Edge Effect Hinders Locating the True Position of an Edge for Critical Dimension Metrology	154
10.5	Achieving High Resolution with Secondary Electrons	156
10.5.1	Beam Energy Strategies	156
10.5.2	Improving the SE ₁ Signal	158
10.5.3	Eliminate the Use of SEs Altogether: "Low Loss BSEs"	161
10.6	Factors That Hinder Achieving High Resolution	163
10.6.1	Achieving Visibility: The Threshold Contrast	163
10.6.2	Pathological Specimen Behavior	163
10.6.3	Pathological Specimen and Instrumentation Behavior	164
	References	164
11	Low Beam Energy SEM	165
11.1	What Constitutes "Low" Beam Energy SEM Imaging?	166
11.2	Secondary Electron and Backscattered Electron Signal Characteristics in the Low Beam Energy Range	166
11.3	Selecting the Beam Energy to Control the Spatial Sampling of Imaging Signals	169
11.3.1	Low Beam Energy for High Lateral Resolution SEM	169
11.3.2	Low Beam Energy for High Depth Resolution SEM	169
11.3.3	Extremely Low Beam Energy Imaging	171
	References	172
12	Variable Pressure Scanning Electron Microscopy (VPSEM)	173
12.1	Review: The Conventional SEM High Vacuum Environment	174
12.1.1	Stable Electron Source Operation	174
12.1.2	Maintaining Beam Integrity	174
12.1.3	Stable Operation of the Everhart-Thornley Secondary Electron Detector	174
12.1.4	Minimizing Contamination	174
12.2	How Does VPSEM Differ From the Conventional SEM Vacuum Environment?	174

12.3	Benefits of Scanning Electron Microscopy at Elevated Pressures	175
12.3.1	Control of Specimen Charging	175
12.3.2	Controlling the Water Environment of a Specimen	176
12.4	Gas Scattering Modification of the Focused Electron Beam	177
12.5	VPSEM Image Resolution	181
12.6	Detectors for Elevated Pressure Microscopy	182
12.6.1	Backscattered Electrons—Passive Scintillator.....	182
12.6.2	Secondary Electrons—Gas Amplification Detector	182
12.7	Contrast in VPSEM	184
	References.....	185
13	ImageJ and Fiji	187
13.1	The ImageJ Universe	188
13.2	Fiji	188
13.3	Plugins	190
13.4	Where to Learn More	191
	References.....	193
14	SEM Imaging Checklist	195
14.1	Specimen Considerations (High Vacuum SEM; Specimen Chamber Pressure <math> < 10^{-3}</math> Pa)	197
14.1.1	Conducting or Semiconducting Specimens	197
14.1.2	Insulating Specimens	197
14.2	Electron Signals Available	197
14.2.1	Beam Electron Range	197
14.2.2	Backscattered Electrons	197
14.2.3	Secondary Electrons	197
14.3	Selecting the Electron Detector	198
14.3.1	Everhart–Thornley Detector (“Secondary Electron” Detector)	198
14.3.2	Backscattered Electron Detectors	198
14.3.3	“Through-the-Lens” Detectors.....	198
14.4	Selecting the Beam Energy for SEM Imaging	198
14.4.1	Compositional Contrast With Backscattered Electrons	198
14.4.2	Topographic Contrast With Backscattered Electrons	198
14.4.3	Topographic Contrast With Secondary Electrons.....	198
14.4.4	High Resolution SEM Imaging	198
14.5	Selecting the Beam Current	199
14.5.1	High Resolution Imaging	199
14.5.2	Low Contrast Features Require High Beam Current and/or Long Frame Time to Establish Visibility	199
14.6	Image Presentation	199
14.6.1	“Live” Display Adjustments	199
14.6.2	Post-Collection Processing	199
14.7	Image Interpretation	199
14.7.1	Observer’s Point of View	199
14.7.2	Direction of Illumination	199
14.7.3	Contrast Encoding	200
14.7.4	Imaging Topography With the Everhart–Thornley Detector.....	200
14.7.5	Annular BSE Detector (Semiconductor Sum Mode A + B and Passive Scintillator)	200
14.7.6	Semiconductor BSE Detector Difference Mode, A–B.....	200
14.7.7	Everhart–Thornley Detector, Negatively Biased to Reject SE	200
14.8	Variable Pressure Scanning Electron Microscopy (VPSEM)	200
14.8.1	VPSEM Advantages	200
14.8.2	VPSEM Disadvantages.....	200
15	SEM Case Studies	201
15.1	Case Study: How High Is That Feature Relative to Another?	202
15.2	Revealing Shallow Surface Relief	204
15.3	Case Study: Detecting Ink-Jet Printer Deposits	206

16	Energy Dispersive X-ray Spectrometry: Physical Principles and User-Selected Parameters	209
16.1	The Energy Dispersive Spectrometry (EDS) Process	210
16.1.1	The Principal EDS Artifact: Peak Broadening (EDS Resolution Function).....	210
16.1.2	Minor Artifacts: The Si-Escape Peak.....	213
16.1.3	Minor Artifacts: Coincidence Peaks.....	213
16.1.4	Minor Artifacts: Si Absorption Edge and Si Internal Fluorescence Peak.....	215
16.2	"Best Practices" for Electron-Excited EDS Operation	216
16.2.1	Operation of the EDS System.....	216
16.3	Practical Aspects of Ensuring EDS Performance for a Quality Measurement Environment	219
16.3.1	Detector Geometry.....	219
16.3.2	Process Time.....	222
16.3.3	Optimal Working Distance.....	222
16.3.4	Detector Orientation.....	223
16.3.5	Count Rate Linearity.....	225
16.3.6	Energy Calibration Linearity.....	226
16.3.7	Other Items.....	227
16.3.8	Setting Up a Quality Control Program.....	228
16.3.9	Purchasing an SDD.....	230
	References.....	234
17	DTSA-II EDS Software	235
17.1	Getting Started With NIST DTSA-II	236
17.1.1	Motivation.....	236
17.1.2	Platform.....	236
17.1.3	Overview.....	236
17.1.4	Design.....	237
17.1.5	The Three -Leg Stool: Simulation, Quantification and Experiment Design.....	237
17.1.6	Introduction to Fundamental Concepts.....	238
17.2	Simulation in DTSA-II	245
17.2.1	Introduction.....	245
17.2.2	Monte Carlo Simulation.....	245
17.2.3	Using the GUI To Perform a Simulation.....	247
17.2.4	Optional Tables.....	262
	References.....	264
18	Qualitative Elemental Analysis by Energy Dispersive X-Ray Spectrometry	265
18.1	Quality Assurance Issues for Qualitative Analysis: EDS Calibration	266
18.2	Principles of Qualitative EDS Analysis	266
18.2.1	Critical Concepts From the Physics of Characteristic X-ray Generation and Propagation.....	266
18.2.2	X-Ray Energy Database: Families of X-Rays.....	269
18.2.3	Artifacts of the EDS Detection Process.....	269
18.3	Performing Manual Qualitative Analysis	275
18.3.1	Why are Skills in Manual Qualitative Analysis Important?.....	275
18.3.2	Performing Manual Qualitative Analysis: Choosing the Instrument Operating Conditions.....	277
18.4	Identifying the Peaks	278
18.4.1	Employ the Available Software Tools.....	278
18.4.2	Identifying the Peaks: Major Constituents.....	280
18.4.3	Lower Photon Energy Region.....	281
18.4.4	Identifying the Peaks: Minor and Trace Constituents.....	281
18.4.5	Checking Your Work.....	281
18.5	A Worked Example of Manual Peak Identification	281
	References.....	287

19	Quantitative Analysis: From k-ratio to Composition	289
19.1	What Is a k-ratio?	290
19.2	Uncertainties in k-ratios.....	291
19.3	Sets of k-ratios	291
19.4	Converting Sets of k-ratios Into Composition	292
19.5	The Analytical Total.....	292
19.6	Normalization	292
19.7	Other Ways to Estimate C_2	293
19.7.1	Oxygen by Assumed Stoichiometry	293
19.7.2	Waters of Crystallization.....	293
19.7.3	Element by Difference.....	293
19.8	Ways of Reporting Composition	294
19.8.1	Mass Fraction	294
19.8.2	Atomic Fraction.....	294
19.8.3	Stoichiometry.....	294
19.8.4	Oxide Fractions.....	294
19.9	The Accuracy of Quantitative Electron-Excited X-ray Microanalysis	295
19.9.1	Standards-Based k-ratio Protocol	295
19.9.2	“Standardless Analysis”	296
19.10	Appendix	298
19.10.1	The Need for Matrix Corrections To Achieve Quantitative Analysis	298
19.10.2	The Physical Origin of Matrix Effects	299
19.10.3	ZAF Factors in Microanalysis	299
	References.....	307
20	Quantitative Analysis: The SEM/EDS Elemental Microanalysis k-ratio Procedure for Bulk Specimens, Step-by-Step	309
20.1	Requirements Imposed on the Specimen and Standards	311
20.2	Instrumentation Requirements	311
20.2.1	Choosing the EDS Parameters	311
20.2.2	Choosing the Beam Energy, E_0	313
20.2.3	Measuring the Beam Current.....	313
20.2.4	Choosing the Beam Current.....	314
20.3	Examples of the k-ratio/Matrix Correction Protocol with DTSA II	316
20.3.1	Analysis of Major Constituents ($C > 0.1$ Mass Fraction) with Well-Resolved Peaks.....	316
20.3.2	Analysis of Major Constituents ($C > 0.1$ Mass Fraction) with Severely Overlapping Peaks	318
20.3.3	Analysis of a Minor Constituent with Peak Overlap From a Major Constituent	319
20.3.4	Ba-Ti Interference in $BaTiSi_3O_9$	319
20.3.5	Ba-Ti Interference: Major/Minor Constituent Interference in K2496 Microanalysis Glass.....	319
20.4	The Need for an Iterative Qualitative and Quantitative Analysis Strategy	319
20.4.1	Analysis of a Complex Metal Alloy, IN100	320
20.4.2	Analysis of a Stainless Steel	323
20.4.3	Progressive Discovery: Repeated Qualitative–Quantitative Analysis Sequences.....	324
20.5	Is the Specimen Homogeneous?	326
20.6	Beam-Sensitive Specimens	331
20.6.1	Alkali Element Migration.....	331
20.6.2	Materials Subject to Mass Loss During Electron Bombardment—the Marshall-Hall Method	334
	References.....	339

21	Trace Analysis by SEM/EDS	341
21.1	Limits of Detection for SEM/EDS Microanalysis	342
21.2	Estimating the Concentration Limit of Detection, C_{DL}	343
21.2.1	Estimating C_{DL} from a Trace or Minor Constituent from Measuring a Known Standard	343
21.2.2	Estimating C_{DL} After Determination of a Minor or Trace Constituent with Severe Peak Interference from a Major Constituent.....	343
21.2.3	Estimating C_{DL} When a Reference Value for Trace or Minor Element Is Not Available	343
21.3	Measurements of Trace Constituents by Electron-Excited Energy Dispersive X-ray Spectrometry	345
21.3.1	Is a Given Trace Level Measurement Actually Valid?.....	345
21.4	Pathological Electron Scattering Can Produce "Trace" Contributions to EDS Spectra	350
21.4.1	Instrumental Sources of Trace Analysis Artifacts.....	350
21.4.2	Assessing Remote Excitation Sources in an SEM-EDS System.....	353
21.5	Summary	357
	References	357
22	Low Beam Energy X-Ray Microanalysis	359
22.1	What Constitutes "Low" Beam Energy X-Ray Microanalysis?	360
22.1.1	Characteristic X-ray Peak Selection Strategy for Analysis.....	364
22.1.2	Low Beam Energy Analysis Range.....	364
22.2	Advantage of Low Beam Energy X-Ray Microanalysis	365
22.2.1	Improved Spatial Resolution.....	365
22.2.2	Reduced Matrix Absorption Correction.....	366
22.2.3	Accurate Analysis of Low Atomic Number Elements at Low Beam Energy.....	366
22.3	Challenges and Limitations of Low Beam Energy X-Ray Microanalysis	369
22.3.1	Reduced Access to Elements.....	369
22.3.2	Relative Depth of X-Ray Generation: Susceptibility to Vertical Heterogeneity.....	372
22.3.3	At Low Beam Energy, Almost Everything Is Found To Be Layered	373
	References	380
23	Analysis of Specimens with Special Geometry: Irregular Bulk Objects and Particles	381
23.1	The Origins of "Geometric Effects": Bulk Specimens	382
23.2	What Degree of Surface Finish Is Required for Electron-Excited X-ray Microanalysis To Minimize Geometric Effects?	384
23.2.1	No Chemical Etching	384
23.3	Consequences of Attempting Analysis of Bulk Materials With Rough Surfaces	385
23.4	Useful Indicators of Geometric Factors Impact on Analysis	386
23.4.1	The Raw Analytical Total.....	386
23.4.2	The Shape of the EDS Spectrum	389
23.5	Best Practices for Analysis of Rough Bulk Samples	391
23.6	Particle Analysis	394
23.6.1	How Do X-ray Measurements of Particles Differ From Bulk Measurements?.....	394
23.6.2	Collecting Optimum Spectra From Particles.....	395
23.6.3	X-ray Spectrum Imaging: Understanding Heterogeneous Materials.....	400
23.6.4	Particle Geometry Factors Influencing Quantitative Analysis of Particles.....	403
23.6.5	Uncertainty in Quantitative Analysis of Particles	405
23.6.6	Peak-to-Background (P/B) Method	408
23.7	Summary	410
	References.....	411

24	Compositional Mapping	413
24.1	Total Intensity Region-of-Interest Mapping	414
24.1.1	Limitations of Total Intensity Mapping	415
24.2	X-Ray Spectrum Imaging	417
24.2.1	Utilizing XSI Datacubes.....	419
24.2.2	Derived Spectra.....	419
24.3	Quantitative Compositional Mapping	424
24.4	Strategy for XSI Elemental Mapping Data Collection	430
24.4.1	Choosing the EDS Dead-Time.....	430
24.4.2	Choosing the Pixel Density.....	432
24.4.3	Choosing the Pixel Dwell Time.....	434
	References.....	439
25	Attempting Electron-Excited X-Ray Microanalysis in the Variable Pressure Scanning Electron Microscope (VPSEM)	441
25.1	Gas Scattering Effects in the VPSEM	442
25.1.1	Why Doesn't the EDS Collimator Exclude the Remote Skirt X-Rays?.....	446
25.1.2	Other Artifacts Observed in VPSEM X-Ray Spectrometry	448
25.2	What Can Be Done To Minimize gas Scattering in VPSEM?	450
25.2.1	Workarounds To Solve Practical Problems.....	451
25.2.2	Favorable Sample Characteristics.....	451
25.2.3	Unfavorable Sample Characteristics.....	456
	References.....	459
26	Energy Dispersive X-Ray Microanalysis Checklist	461
26.1	Instrumentation	462
26.1.1	SEM.....	462
26.1.2	EDS Detector	462
26.1.3	Probe Current Measurement Device	462
26.1.4	Conductive Coating	463
26.2	Sample Preparation	463
26.2.1	Standard Materials	464
26.2.2	Peak Reference Materials.....	464
26.3	Initial Set-Up	464
26.3.1	Calibrating the EDS Detector.....	464
26.4	Collecting Data	466
26.4.1	Exploratory Spectrum	466
26.4.2	Experiment Optimization.....	467
26.4.3	Selecting Standards	467
26.4.4	Reference Spectra.....	467
26.4.5	Collecting Standards.....	467
26.4.6	Collecting Peak-Fitting References	467
26.4.7	Collecting Spectra From the Unknown	467
26.5	Data Analysis	468
26.5.1	Organizing the Data.....	468
26.5.2	Quantification	468
26.6	Quality Check	468
26.6.1	Check the Residual Spectrum After Peak Fitting	468
26.6.2	Check the Analytic Total	469
26.6.3	Intercompare the Measurements	469
	Reference.....	470
27	X-Ray Microanalysis Case Studies	471
27.1	Case Study: Characterization of a Hard-Facing Alloy Bearing Surface	472
27.2	Case Study: Aluminum Wire Failures in Residential Wiring	474
27.3	Case Study: Characterizing the Microstructure of a Manganese Nodule	476
	References.....	479

28	Cathodoluminescence	481
28.1	Origin	482
28.2	Measuring Cathodoluminescence	483
28.2.1	Collection of CL	483
28.2.2	Detection of CL.....	483
28.3	Applications of CL	485
28.3.1	Geology.....	485
28.3.2	Materials Science	485
28.3.3	Organic Compounds.....	489
	References.....	489
29	Characterizing Crystalline Materials in the SEM	491
29.1	Imaging Crystalline Materials with Electron Channeling Contrast	492
29.1.1	Single Crystals.....	492
29.1.2	Polycrystalline Materials.....	494
29.1.3	Conditions for Detecting Electron Channeling Contrast	496
29.2	Electron Backscatter Diffraction in the Scanning Electron Microscope	496
29.2.1	Origin of EBSD Patterns	498
29.2.2	Cameras for EBSD Pattern Detection.....	499
29.2.3	EBSD Spatial Resolution.....	499
29.2.4	How Does a Modern EBSD System Index Patterns.....	501
29.2.5	Steps in Typical EBSD Measurements.....	502
29.2.6	Display of the Acquired Data	505
29.2.7	Other Map Components.....	508
29.2.8	Dangers and Practice of "Cleaning" EBSD Data	508
29.2.9	Transmission Kikuchi Diffraction in the SEM.....	509
29.2.10	Application Example.....	510
29.2.11	Summary	513
29.2.12	Electron Backscatter Diffraction Checklist.....	513
	References.....	514
30	Focused Ion Beam Applications in the SEM Laboratory	517
30.1	Introduction	518
30.2	Ion-Solid Interactions	518
30.3	Focused Ion Beam Systems	519
30.4	Imaging with Ions	520
30.5	Preparation of Samples for SEM	521
30.5.1	Cross-Section Preparation.....	522
30.5.2	FIB Sample Preparation for 3D Techniques and Imaging.....	524
30.6	Summary	526
	References.....	528
31	Ion Beam Microscopy	529
31.1	What Is So Useful About Ions?	530
31.2	Generating Ion Beams	533
31.3	Signal Generation in the HIM	534
31.4	Current Generation and Data Collection in the HIM	536
31.5	Patterning with Ion Beams	537
31.6	Operating the HIM	538
31.7	Chemical Microanalysis with Ion Beams	538
	References.....	539
	Supplementary Information	541
	Appendix.....	542
	Index	547